



Attorney's Docket No. 1836-001630

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TC 1700

AMENDMENT TRANSMITTAL LETTER

BOX AF

Commissioner for Patents  
Washington, D.C. 20231

Serial No.: 09/714,424 Filing Date: November 16, 2000  
Examiner: Allan R. Kuhns Group Art Unit: 1732  
Invention: "High Performance Microcellular Foam and Manufacturing Method and Apparatus Thereof"

Transmitted herewith is an Amendment in the above-identified application.

- ☒ Small Entity Status is/has been asserted for this application under 37 CFR 1.27.  
☐ A verified statement to establish small entity status under 37 CFR 1.27 is enclosed.  
☐ No additional fee is required.  
☒ The fee has been calculated as shown below:

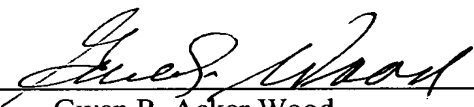
No. of Claims After Amendment	Highest No. Previously Paid For	Present Extra	Small Entity Rate	Non-Small Entity Rate	Charge
Total 19	20	0	x \$ 9.00	x \$ 18.00	\$ 00.00
Indep. 4	3	1	x \$ 42.00	x \$ 84.00	\$ 42.00
First Presentation of Multiple Dependent Claim/s			+ \$140.00	+ \$280.00	\$ 00.00
TOTAL ADDITIONAL FEE					\$ 42.00

- ☒ Check in the amounts of \$42.00 is enclosed to cover the excess claim fee.  
☒ Check in the amount of \$465.00 is enclosed for a 3 month Petition for Extension of Time.  
☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication to Deposit Account No. 23-0650. Please refund any overpayment to Deposit Account No. 23-0650. An original and two copies of this sheet are enclosed.  
☒ Any additional filing fees required under 37 CFR 1.16.  
☒ Any patent application processing fees under 37 CFR 1.17.

February 13, 2003

Date

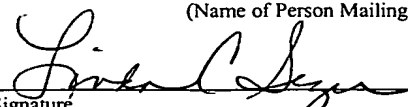
By

  
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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231 on February 13, 2003

Linda C. Seger

(Name of Person Mailing Paper)

  
Signature

02/13/2003

Date